



Material Content Data Sheet



Sales Product Name		TLE8444SL		Issued		25. September 2017		
MA#		MA000982450						
Package		PG-SSOP-24-7		Weight*		147.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.653	4.51	4.51	45131	45131
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		422	
	non noble metal	iron	7439-89-6	1.245	0.84		8448	
wire	non noble metal	copper	7440-50-8	50.568	34.30	35.19	343031	352007
	noble metal	gold	7440-57-5	0.716	0.49	0.49	4860	4860
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1137
plastics		epoxy resin	-	7.714	5.23		52325	
	inorganic material	silicondioxide	60676-86-0	75.961	51.54	56.88	515286	568748
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11395	11395
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2478	2478
glue	plastics	acrylic resin	-	0.499	0.34		3384	
	noble metal	silver	7440-22-4	1.769	1.20	1.54	11997	15381
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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